



VMDSEMI

VUSK002R30ANA

Datasheet

General Description

VUSK002R30ANA MOSFET is based on unique device design to achieve low $R_{DS(ON)}$, ESD Protected Up to 2.0KV (HBM).

Symbol

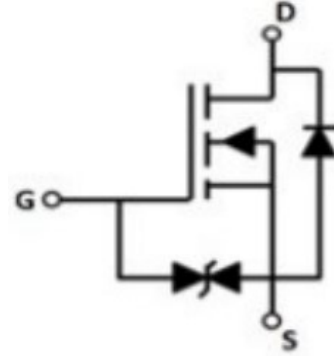


Figure 1 Symbol of VUSK002R30ANA

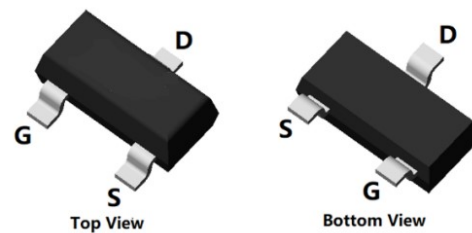
Features

- $R_{DS(ON)_{max}} = 300.0m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)_{max}} = 400m\Omega @ V_{GS} = 2.5V$
- Trench Power LV MOSFET technology
- High Power and current handling capability

Application

- Load Switch
- Power Management
- Interfacing, Logic switch

Package Type



SOT-523

Figure 2 Package Type of VUSK002R30ANA

Ordering Information

Product Name	Package
VUSK002R30ANA	SOT-523

Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current $T_A = 25^\circ\text{C}@$ Steady state	I_D	0.5	A
Continuous Drain Current $T_A = 70^\circ\text{C}@$ Steady state		0.4	A
Pulsed Drain Current ^{Note1}	I_{DM}	3.3	A
Total Power Dissipation $T_A = 25^\circ\text{C}$	P_D	0.18	W
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note2}	$R_{\theta JA}$		694		$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$		± 2.0	± 10	μA
		$V_{GS} = \pm 8V, V_{DS} = 0V$		± 0.5	± 2	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.35	0.75	1.1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=0.5A$		220	300	$m\Omega$
		$V_{GS}=2.5V, I_D=0.4A$		290	400	
		$V_{GS}=1.8V, I_D=0.2A$		420	700	
Gate Resistance	R_g	$F=1MHz, \text{Open drain}$		50		Ω
Dynamic Characteristics ^{Note2}						
Input Capacitance	C_{ISS}	$V_{DS}=10V$		56		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		20		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		2.5		pF
Switching Parameters ^{Note3}						
Gate to Source Charge	Q_{gs}	$V_{DS}=10V$		0.28		nC
Gate to Drain Charge	Q_{gd}	$V_{GS}=4.5V$		0.22		
Gate Charge Total	Q_g	$I_D=0.5A$		1.0		
Reverse Recovery Charge	Q_{rr}	$I_F=0.5A$		0.4		ns
Reverse Recovery Time	t_{rr}	$di/dt=20A/\mu s$		14.4		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V$		2		
Turn-on Rise Time	t_r	$V_{GS}=4.5V$		18.8		
Turn-off Delay Time	$t_{d(off)}$	$I_D=0.5A$		10		
Turn-off Fall Time	t_f	$R_G=10\Omega$		23		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S=0.5A$			1.2	V
Maximum Body-Diode Continuous Current	I_S				0.5	A

Notes :

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. These parameters have no way to verify.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$.

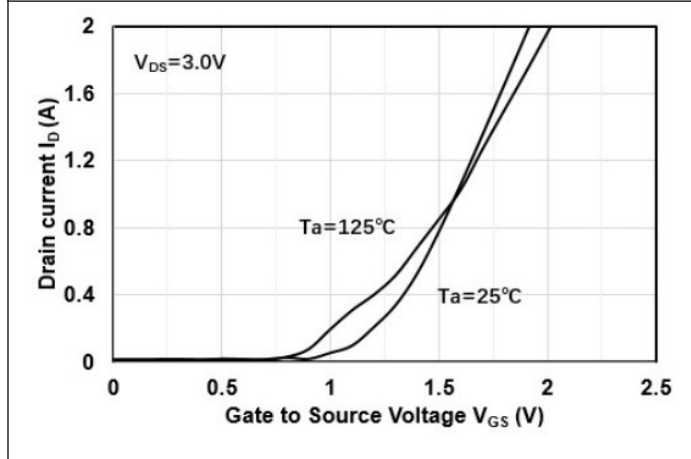
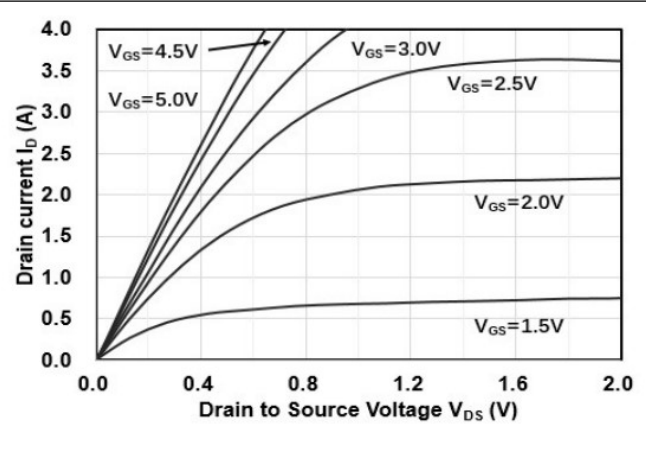
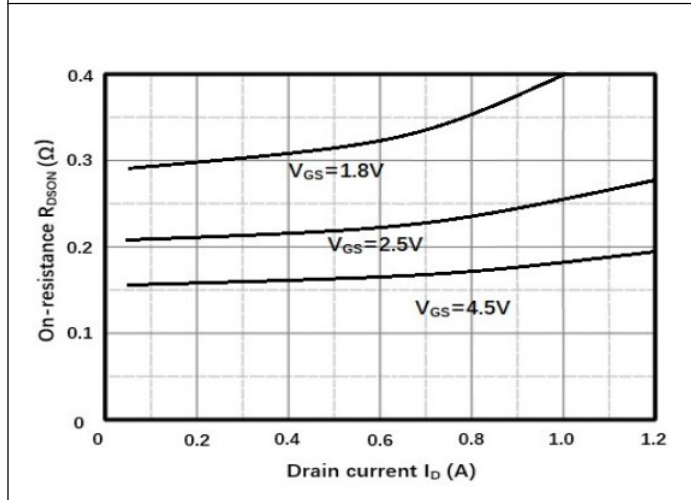
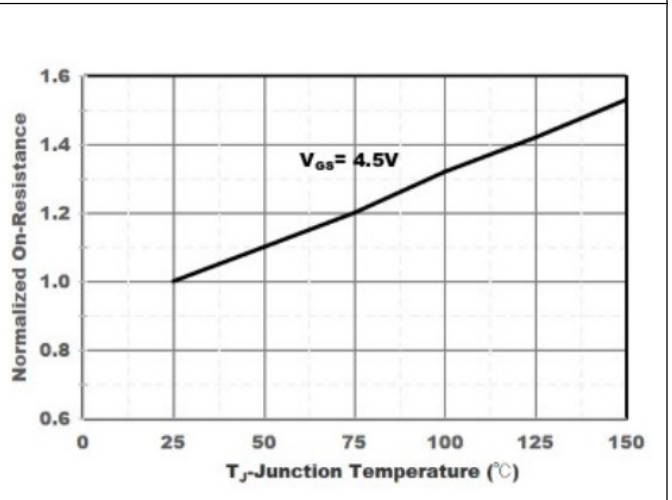
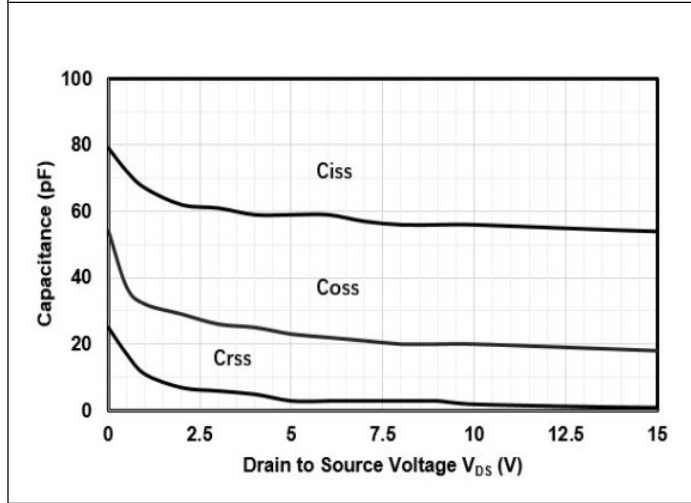
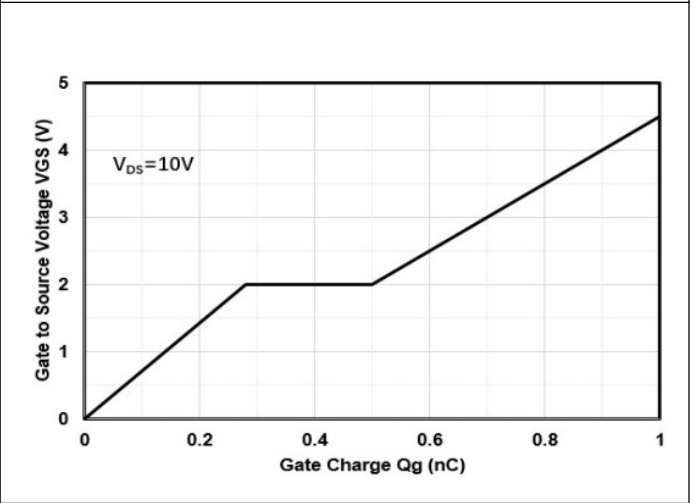
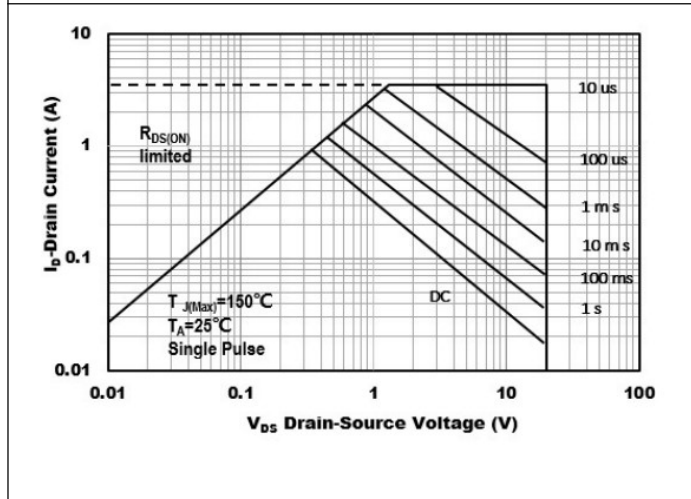
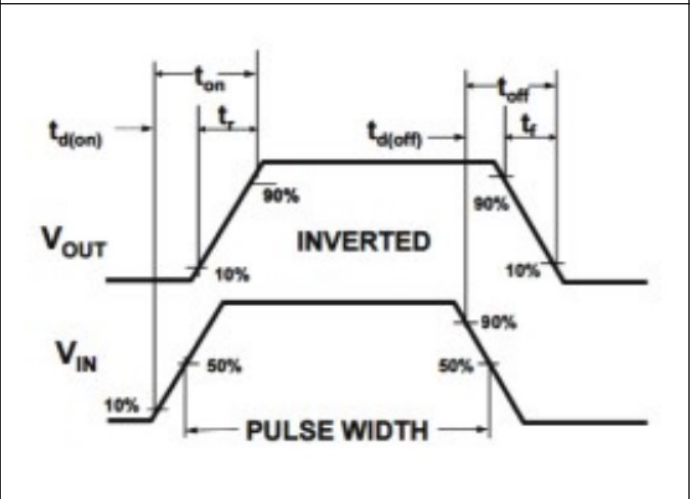
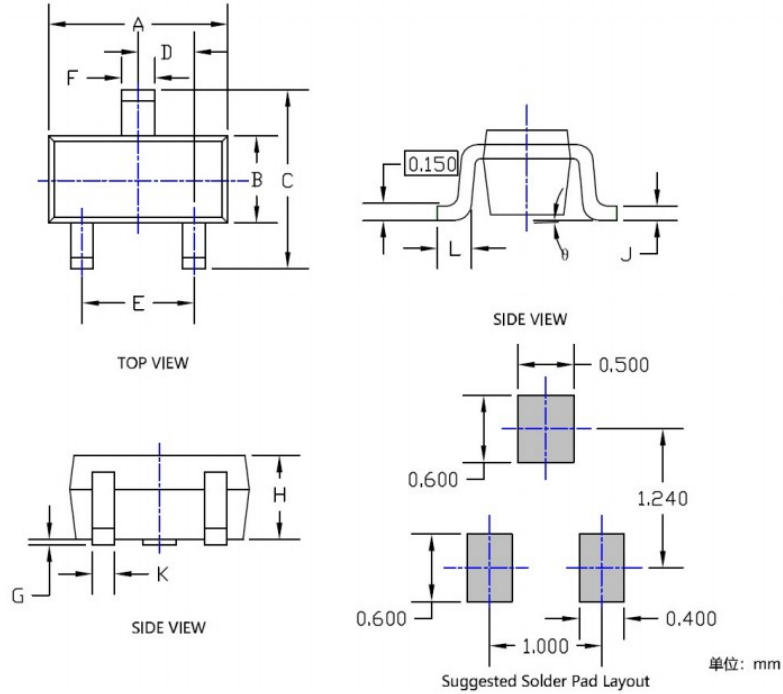
Typical Performance Characteristics
Figure 3: Transfer Characteristics

Figure 4: Output Characteristics

Figure 5: On-Resistance vs. Drain Current and Gate Voltage

Figure 6: On-Resistance vs. Junction Temperature


Figure 7: Capacitance Characteristics

Figure 8: Gate Charge

Figure 9: Safe Operation Area

Figure 10: Switching Wave


Mechanical Dimensions:
SOT-523 Package Information


Symbo	Dimensions In Millimeters			Dimensions In Inches		
	Min.	NOM.	Max.	Min.	NOM.	Max.
A	0.059	0.063	0.067	1.500	1.600	1.700
B	0.030	0.031	0.033	0.750	0.800	0.850
C	0.057	0.063	0.069	1.450	1.600	1.750
D	0.020TYP			0.500TYP		
E	0.035	0.039	0.043	0.900	1.000	1.100
F	0.010	0.014	0.018	0.250	0.350	0.450
G	0.000	--	0.004	0.000	--	0.100
H	0.024	0.028	0.031	0.600	0.700	0.800
J	0.004	--	0.008	0.100	--	0.200
K	0.006	0.010	0.014	0.150	0.250	0.350
L	0.010	--	0.018	0.260	--	0.460
θ	0°	--	8°	0°	--	8°

Note:

1. Package body sizes exclude mode flash and gate burrs.
2. Tolerance 0.1mm unless otherwise specified.
3. The pad layout is for reference purposes only.

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Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shenzhen

Shenzhen Sales Center.
17B, No.1 Phoenix Building, 2008 Shennan Road,
Shenzhen, P.R of China
Tel: +86-0755- 82570682